

Amendments to the Claims:

Kindly delete Claims 10 and 18-23, without prejudice.

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Please amend the claims as shown and add new Claims 24-29.

1. (Cancelled)

2. (Currently Amended) A method of forming a honeycomb sandwich composite panel by a resin transfer molding process consisting of:

stacking a thermosetting sealing material on at least one side of a honeycomb core, said thermosetting sealing material having an adhesive property and ~~being a~~ consisting of resin film ~~including and~~ glass microspheres;

stacking a dry fabric on said thermosetting sealing material;

hardening said sealing material by heating said sealing material and said dry fabric up to the curing temperature of said sealing material at a rate of 1°C per minute or less and maintaining this temperature for a specified curing time period of said sealing material;

impregnating said dry fabric with a thermosetting resin while varying the temperature of said sealing material and said dry fabric to a resin impregnating temperature and maintaining this temperature for a specified period of time; and

hardening the resin impregnated into said dry fabric by heating said sealing material and said dry fabric to the curing temperature of said thermosetting resin and hot-pressing them for a specified period of time.

3-15 (Cancelled)

16. (Currently Amended) The method of forming a honeycomb sandwich composite panel according to Claim 2, wherein:

said curing temperature of said sealing material is about ~~1205°C~~ 120 ± 5°C, and said specified curing time period is about ~~13010~~ 130 ± 10 minutes.

17. (Previously Presented) The method of forming a honeycomb sandwich composite panel according to Claim 2, wherein:

said sealing material is ~~[[a]] laminated film formed by laminating~~ a plurality of said thermosetting resin films ~~including said glass microspheres.~~

18.-23. (Cancelled)

24. (New) A method of forming a honeycomb sandwich composite panel by a resin transfer molding process comprising:

stacking a thermosetting sealing material having an adhesive property on at least one side of a honeycomb core, said thermosetting sealing material consisting of a plurality of epoxy resin adhesive films and a carrier material used as an adhesive film placed between said epoxy resin films;

stacking a dry fabric on said thermosetting sealing material;

hardening said sealing material by heating said sealing material and said dry fabric to the curing temperature of said sealing material at a rate of 1°C per minute or less and maintaining this temperature for a specified curing time period of said sealing material;

impregnating said dry fabric with a thermosetting resin while varying the temperature of said sealing material and said dry fabric to a resin impregnating temperature and maintaining this temperature for a specified period of time; and

hardening the resin impregnated into said dry fabric by heating said sealing material and said dry fabric to the curing temperature of said thermosetting resin and hot-pressing them for a specified period of time.

25. (New) The method of forming a honeycomb sandwich composite panel according to claim 24, wherein:

said curing temperature of said sealing material is about $120 \pm 5^{\circ}\text{C}$ and said specified curing time period is about 130 ± 10 minutes.

26. (New) A method of forming a honeycomb sandwich composite panel by a resin transfer molding process comprising:

stacking a thermosetting sealing material having an adhesive property on at least one side of a honeycomb core, said thermosetting sealing material consisting of epoxy resin adhesive films and an epoxy resin film placed between said epoxy resin films;

stacking a dry fabric on said thermosetting sealing material;

hardening said sealing material by heating said sealing material and said dry fabric up to the curing temperature of said sealing material at a rate of 1°C per minute or less and maintaining this temperature for a specified curing time eriod of said sealing material;

impregnating said dry fabric with a thermosetting resin while varying the temperature of said sealing material and said dry fabric to a resin impregnating temperature and maintaining this temperature for a specified period of time; and

hardening the resin impregnated into said dry fabric by heating said sealing material and said dry fabric to the curing temperature of said thermosetting resin and hot-pressing them for a specified period of time.

27. (New) The method of forming a honeycomb sandwich composite panel according to claim 26, wherein:

said curing temperature of said sealing material is about $120 \pm 5^{\circ}\text{C}$ and said specified curing time period is about 130 ± 10 minutes.

28. (New) A method of forming a honeycomb sandwich composite panel by a resin transfer molding process comprising:

stacking a thermosetting sealing material having an adhesive property on at least one side of a honeycomb core, said thermosetting sealing material consisting of three epoxy resin adhesive films;

stacking a dry fabric on said thermosetting sealing material;

hardening said sealing material by heating said sealing material and said dry fabric up to the curing temperature of said sealing material at a rate of 1°C per minute or less and maintaining this temperature for a specified curing time period of said sealing material;

impregnating said dry fabric with a thermosetting resin while varying the temperature of said sealing material and said dry fabric to a resin impregnating temperature and maintaining this temperature for a specified period of time; and

hardening the resin impregnated into said dry fabric by heating said sealing material and said dry fabric to the curing temperature of said thermosetting resin and hot-pressing them for a specified period of time.

29. (New) The method of forming a honeycomb sandwich composite panel according to claim 28, wherein:

said curing temperature of said sealing material is about $120 \pm 5^{\circ}\text{C}$ and said specified curing time period is about 130 ± 10 minutes.